

4 Board Layout, Schematic, and Bill of Materials

4.1 Board Layout

Figure 6 through Figure 11 illustrate the board layouts for this EVM.

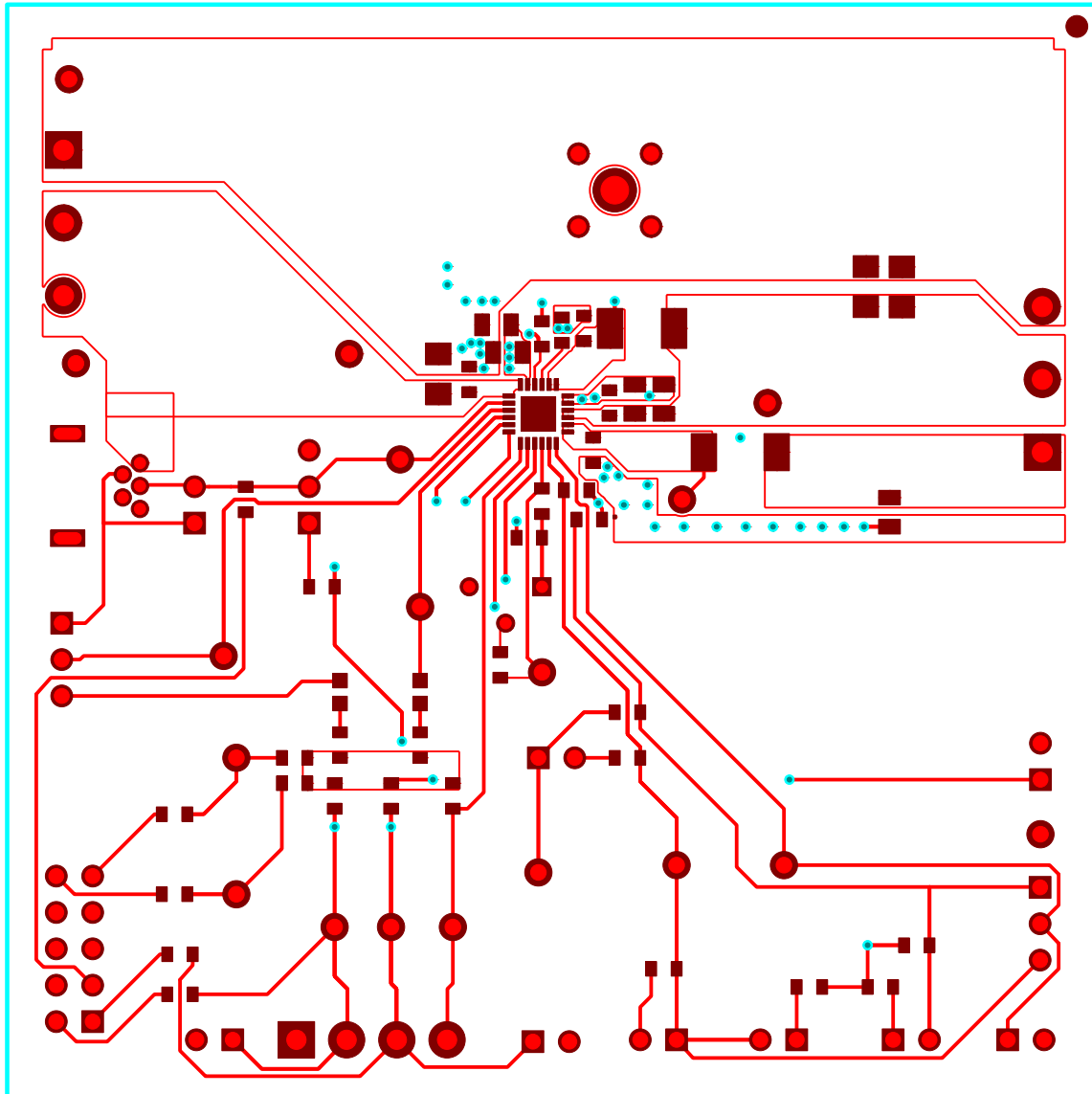


Figure 6. bq24x9xEVM Top Layer

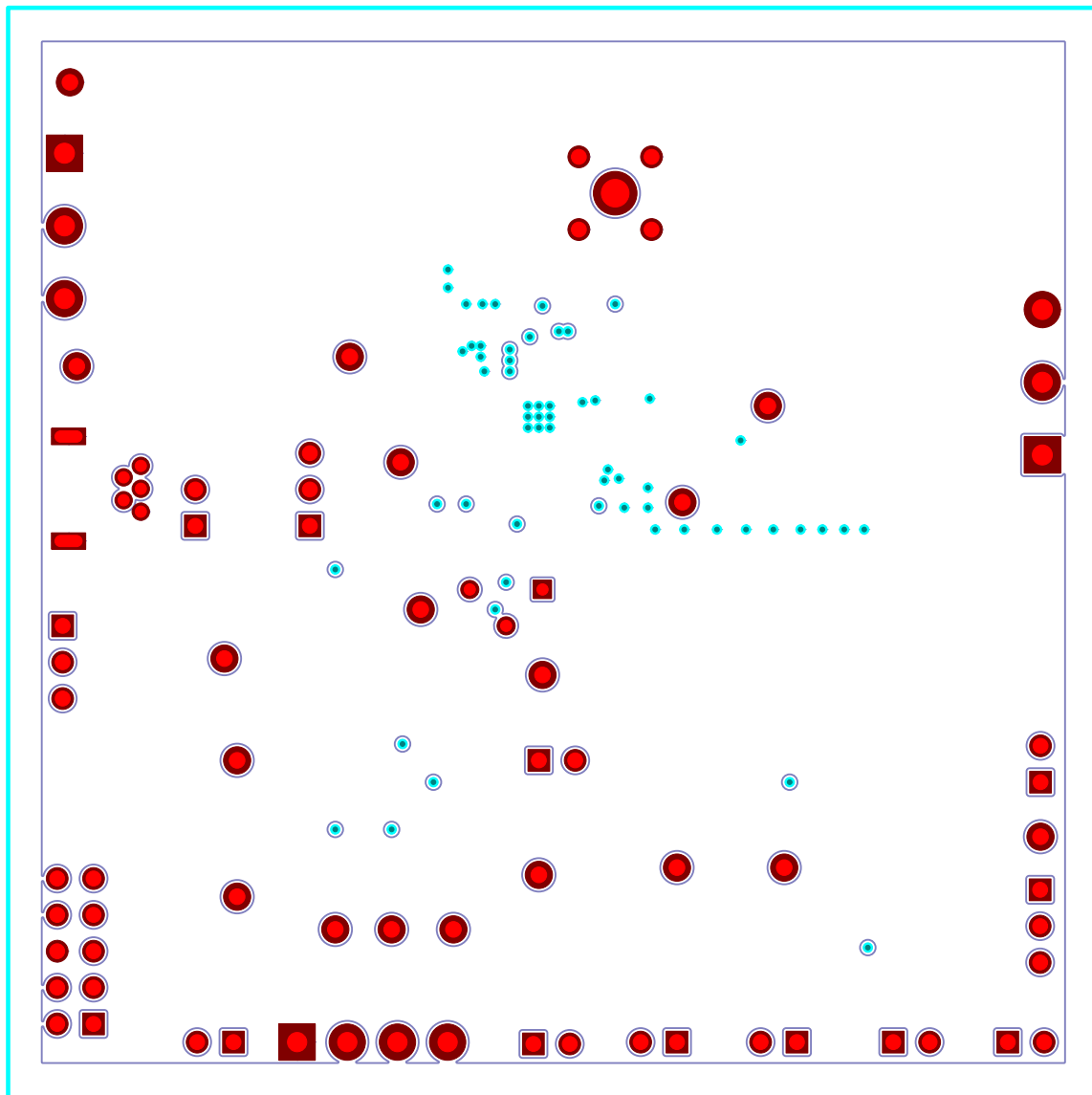


Figure 7. bq24x9xEVM Second Layer

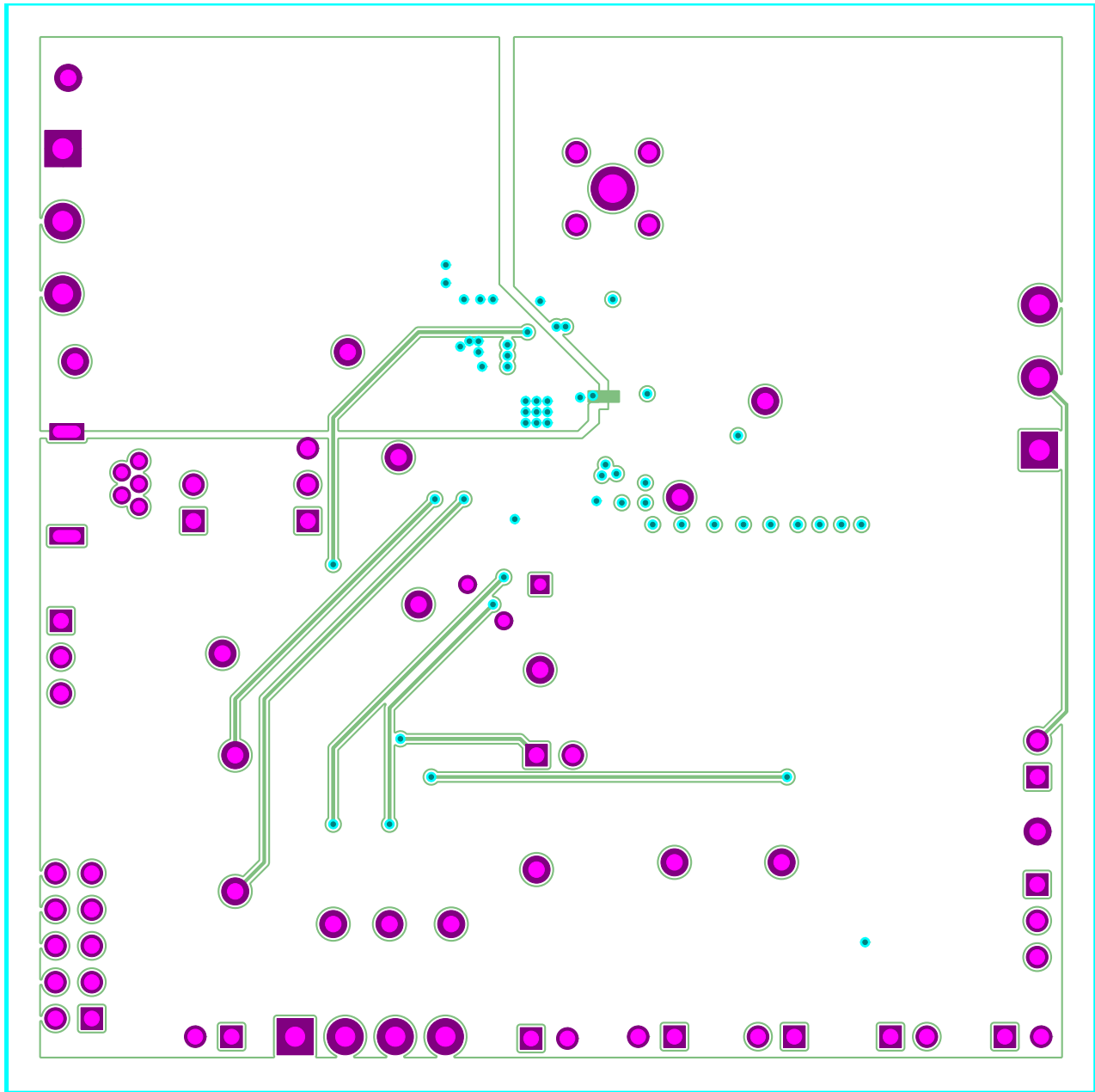


Figure 8. bq24x9xEVM Third Layer

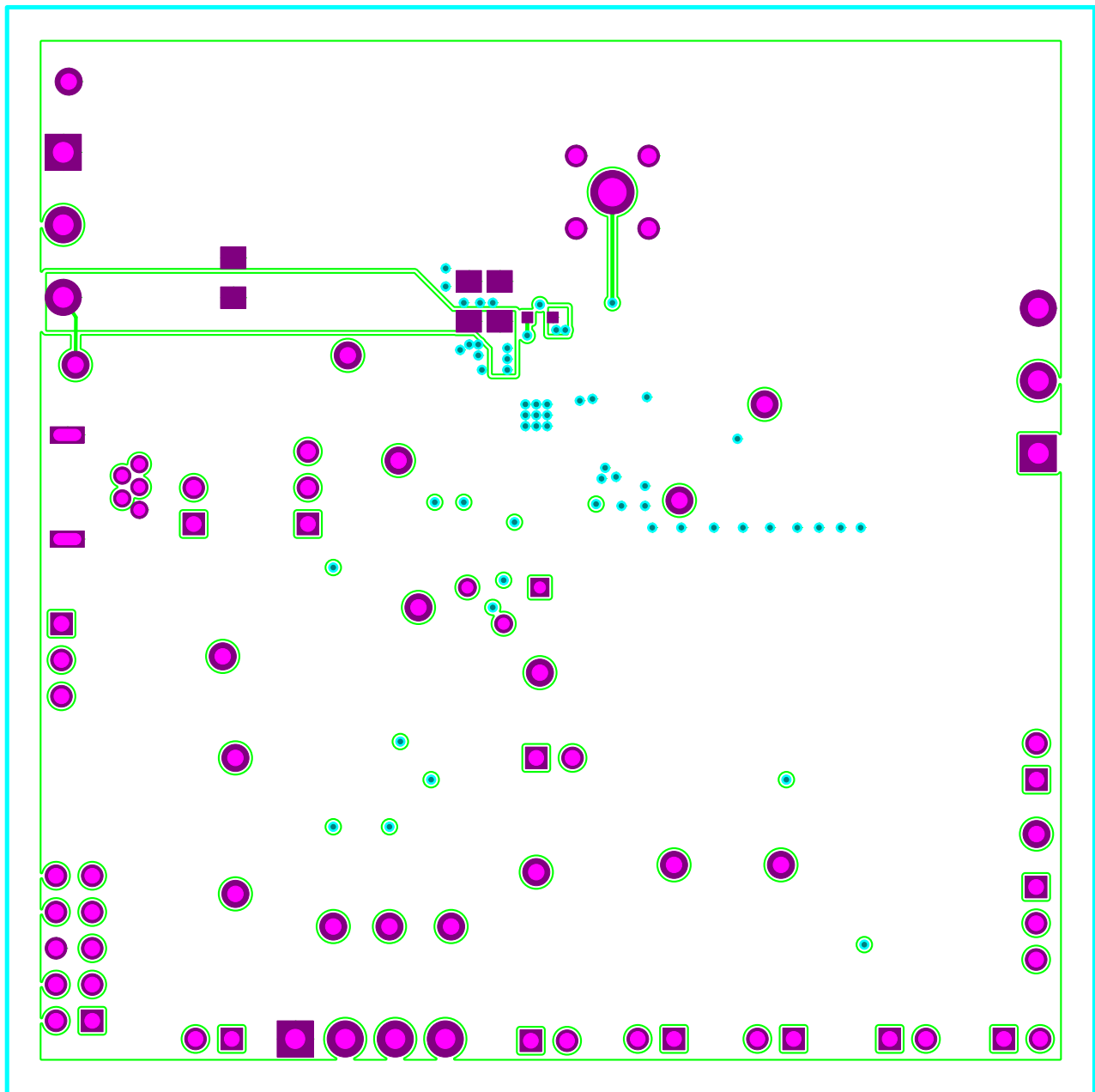


Figure 9. bq24x9xEVM Bottom Layer

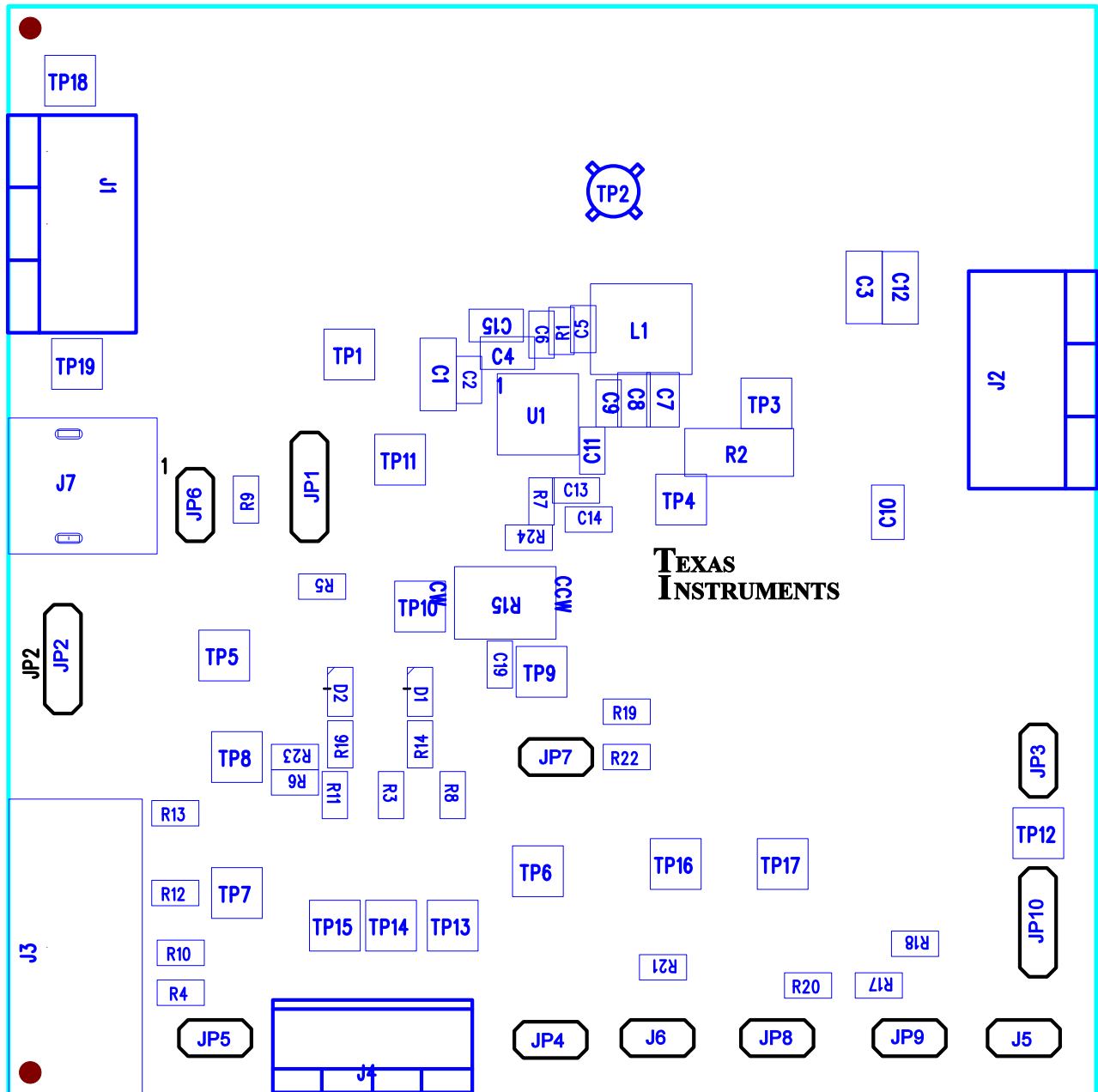


Figure 10. bq24x9xEVM Top Assembly

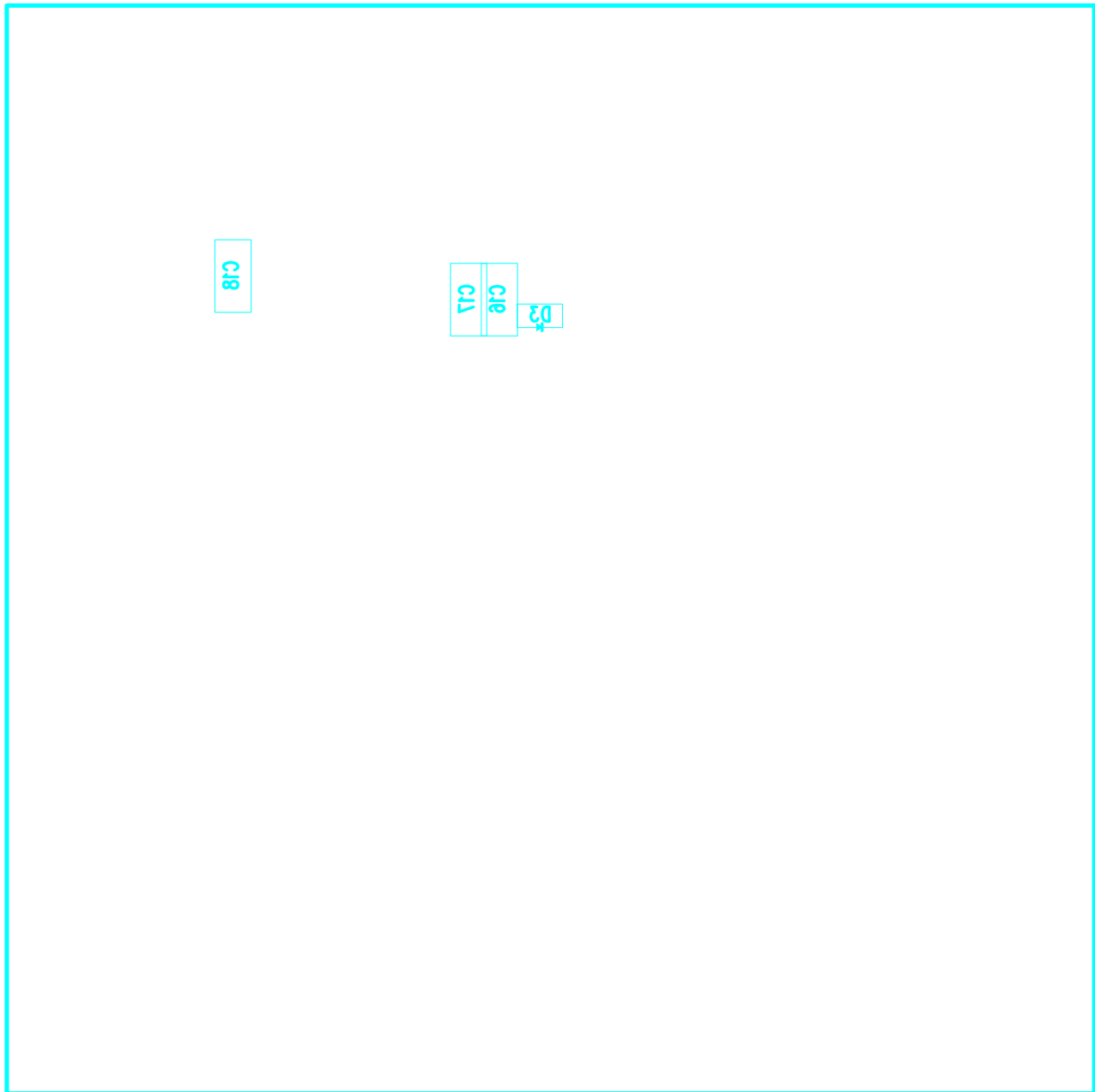


Figure 11. bq24x9xEVM Bottom Assembly

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